



Materials Declaration Form


IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-10-27
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement			
<p>While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.</p>			
Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	B55W*UN18DC6	A	0959	2017-10-27
Amount	UoM	Unit type	ST ECOPACK Grade	
349.70	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFP	10-10-1.4	64	gull wing	
Comment	Package: LQFP 64 10x10x1.4 1. MDF valid for CPs: MS84DCTR - L9662TR - L9662			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	2.99	Leadframe	8550

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	B55W*UN18DC6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	40.860	mg	supplier	die	Silicon (Si)	7440-21-3		39.222	mg	959912	112159
				supplier	metallization	Aluminium (Al)	7429-90-5		0.258	mg	6314	738
				supplier	metallization	Tungsten (W)	7440-33-7		0.409	mg	10010	1170
				supplier	Passivation	Silicon Nitride	12033-89-5		0.063	mg	1542	180
				supplier	Passivation	Silicon Oxide	7631-86-9		0.604	mg	14782	1727
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.304	mg	7440	869
Leadframe	Copper & its alloys	102.145	mg	supplier	alloy	Copper (Cu)	7440-50-8		95.888	mg	938744	274201
				supplier	alloy	Nickel (Ni)	7440-02-0		2.990	mg	29272	8550
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.150	mg	1468	429
				supplier	alloy	Silicon (Si)	7440-21-3		0.648	mg	6344	1853
				supplier	metallization	Silver (Ag)	7440-22-4		2.469	mg	24172	7060
Die attach	Other Organic Materials	9.975	mg	supplier	glue	Silver (Ag)	7440-22-4		9.027	mg	904962	25814
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.549	mg	55038	1570
				supplier	glue	Bismaleimide resin	35325-39-4		0.399	mg	40000	1141
Bonding wires	Other inorganic materials	2.068	mg	supplier	wire	Gold (Au)	7440-57-5		2.048	mg	990329	5856
				supplier	wire	Copper (Cu)	7440-50-8		0.012	mg	5803	34
				supplier	wire	Palladium (Pd)	7440-05-3		0.006	mg	2901	17
				supplier	wire	Platinum (Pt)	7440-06-4		0.002	mg	967	6
Encapsulation	Other Organic Materials	191.087	mg	supplier	mold compound	Silica, vitreous	60676-86-0		166.437	mg	871001	475942
				supplier	mold compound	Epoxy Resin	85954-11-6		15.287	mg	80000	43715
				supplier	mold compound	Phenol Resin	26834-02-6		7.644	mg	40003	21859
				supplier	mold compound	Carbon black	1333-86-4		0.955	mg	4998	2731
Connections coating	Solder	3.565	mg	supplier	mold compound	Bismuth (Bi)	7440-69-9		0.764	mg	3998	2185
				supplier	solder alloy	Tin (Sn)	7440-31-5		3.565	mg	1000000	10194